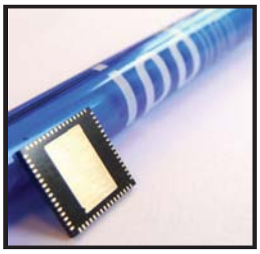
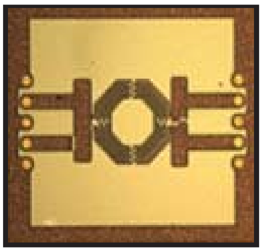
micross components

Announces global distribution agreement with ipdia

The 3D Silicon Leader

Micross Components are pleased to announce their partnership with IPDiA, the leader in 3D silicon solution





IPDiA has developed unique High Density PICS technology, which brings unprecedented results for 3D Silicon capacitors, Silicon RF, Silicon Sub-mounts and customised solutions.

Combining our expertise with both active and passive components, Micross Components are able to offer our customers a high quality solution, whatever their application:

- Mil/Aerospace
- High Temperature
- High Reliability
- Medical
- RF & telecommunications
- Signal coupling
- Power supply decoupling
- DC/DC power conversion

Benefits of using PICS technology

(Passive Integrated Component in Silicon)

Electrical Characteristics

- Up to 10 x better performance*
- Less power consumption
- Low leakage (<40nA)
- Ultra low ESR (<40mΩ)
- Ultra low ESL (<50pH)
- High reliability
- High temp (250°C)
- Longer battery life

Mechanical Characteristics

- Size & volume reduction
- Thin profile (1uF @100µm)
- No crack phenomena
- Cost saving
- IP protection
- Custom-made components for miniaturisation available
- Oversize of Capacitor not required

(*compared to ceramic)

For additional information & world-wide sales support, please contact:

email: chipcomponents@micross.com
web: www.micross.com
phone: +44(0)1603 788967

micross components
Distribution Division